

## 1.5A, 200V - 600V High Efficient Surface Mount Rectifiers

### FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Fast switching for high efficiency
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21



**DO-214AC (SMA)**

### MECHANICAL DATA

**Case:** DO-214AC (SMA)

Molding compound: UL flammability classification rating 94V-0

Part No. with suffix "H" means AEC-Q101 qualified

Packing code with suffix "G" means green compound (halogen-free)

Moisture sensitivity level: level 1, per J-STD-020

**Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 2 whisker test

**Polarity:** Indicated by cathode band

**Weight:** 0.064 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T <sub>A</sub> =25°C unless otherwise noted)					
PARAMETER	SYMBOL	BYG20D	BYG20G	BYG20J	UNIT
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	400	600	V
Maximum RMS voltage	V <sub>RMS</sub>	140	280	420	V
Maximum DC blocking voltage	V <sub>DC</sub>	200	400	600	V
Maximum average forward rectified current	I <sub>F(AV)</sub>	1.5			A
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30			A
Maximum instantaneous forward voltage (Note 1)	V <sub>F</sub>	I <sub>F</sub> =1.0A	1.3		V
		I <sub>F</sub> =1.5A	1.4		
Maximum reverse current @ rated V <sub>R</sub>	I <sub>R</sub>	T <sub>J</sub> =25°C	1		μA
		T <sub>J</sub> =100°C	10		
Pulse energy in avalanche mode, non repetitive (Inductive load switch off), L=120mH	E <sub>RSM</sub>	20			mJ
Maximum reverse recovery time (Note 2)	t <sub>rr</sub>	75			ns
Typical thermal resistance (Note 3)	R <sub>θJL</sub>	25			°C/W
	R <sub>θJA</sub>	100			
Operating junction temperature range	T <sub>J</sub>	- 55 to +150			°C
Storage temperature range	T <sub>STG</sub>	- 55 to +150			°C

Note 1: Pulse test with PW=300μs, 1% duty cycle

Note 2: Reverse recovery test conditions: I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

Note 3: Mount on PC board with 5mm x 5mm copper pads as heatsink.

ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
BYG20x (Note 1)	H	R3	G	SMA	1,800 / 7" Plastic reel
		R2		SMA	7,500 / 13" Paper reel
		M2		SMA	7,500 / 13" Plastic reel
		F3		Folded SMA	1,800 / 7" Plastic reel
		F2		Folded SMA	7,500 / 13" Paper reel
		F4		Folded SMA	7,500 / 13" Plastic reel

Note 1: "x" defines voltage from 200V (BYG20D) to 600V (BYG20J)

EXAMPLE					
EXAMPLE PART NO.	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
BYG20DHR3G	BYG20D	H	R3	G	AEC-Q101 qualified Green compound

**RATINGS AND CHARACTERISTICS CURVES**

(T<sub>A</sub>=25°C unless otherwise noted)

FIG.1 FORWARD CURRENT DERATING CURVE

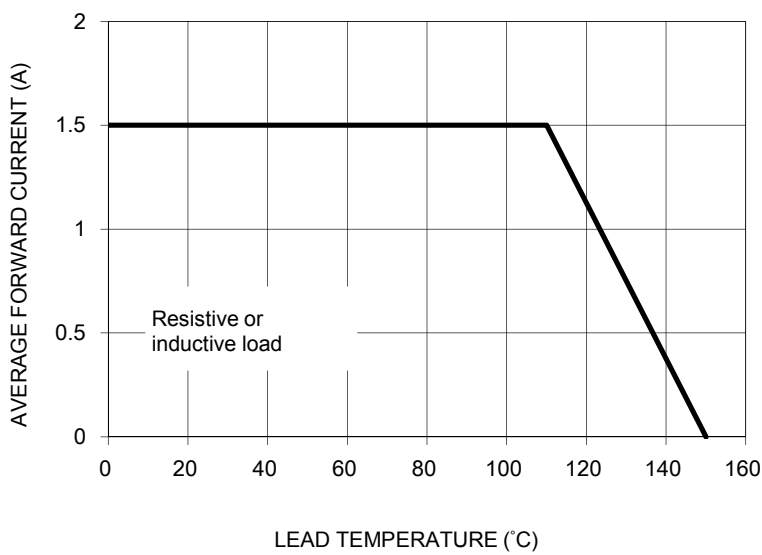


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

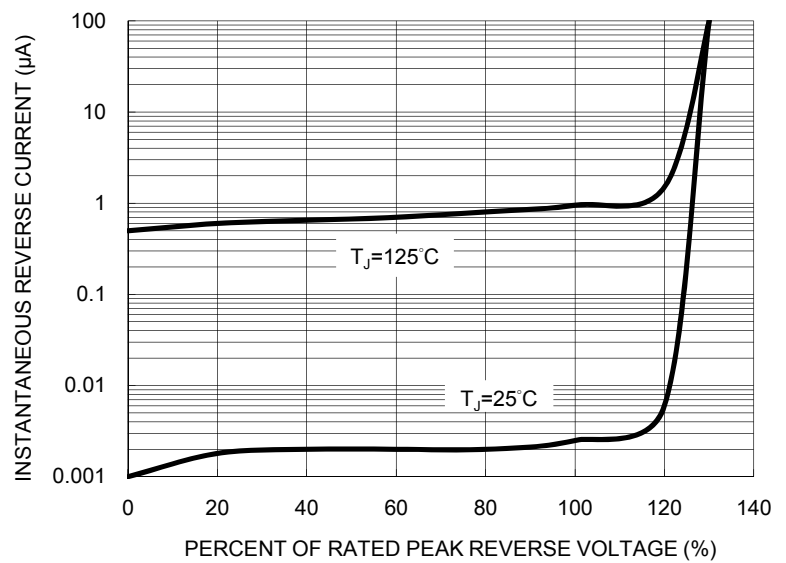


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

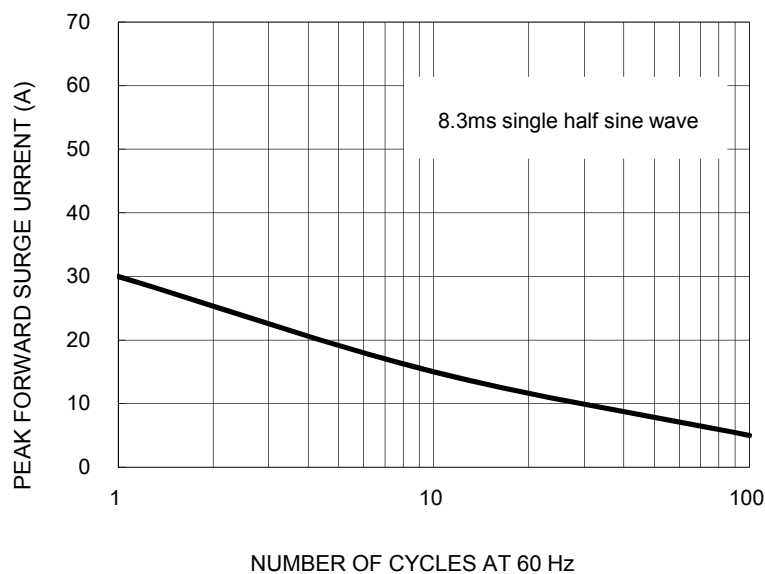


FIG. 4 TYPICAL FORWARD CHARACTERISTICS

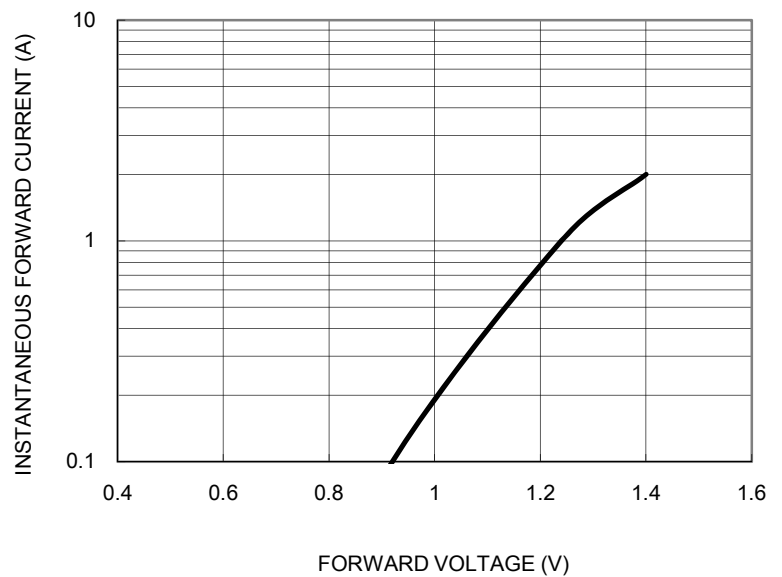


FIG. 5 TYPICAL JUNCTION CAPACITANCE

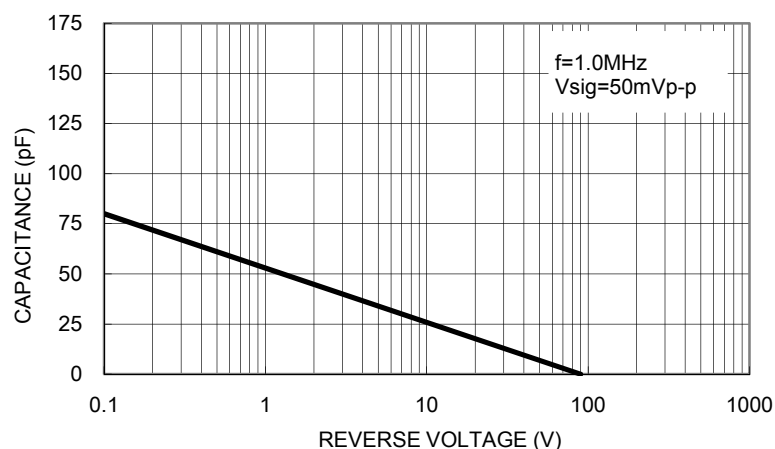
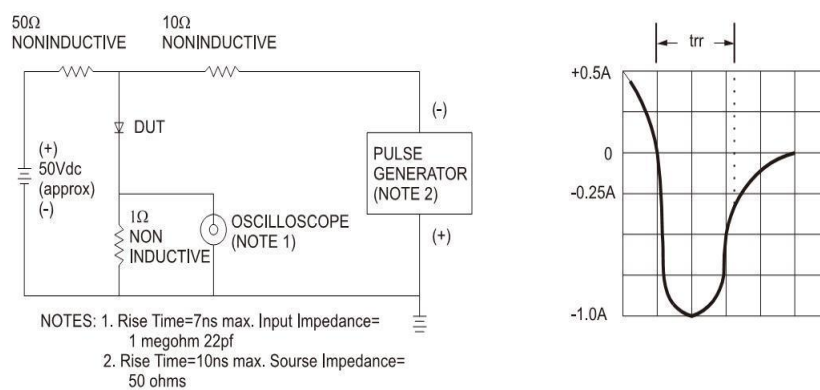
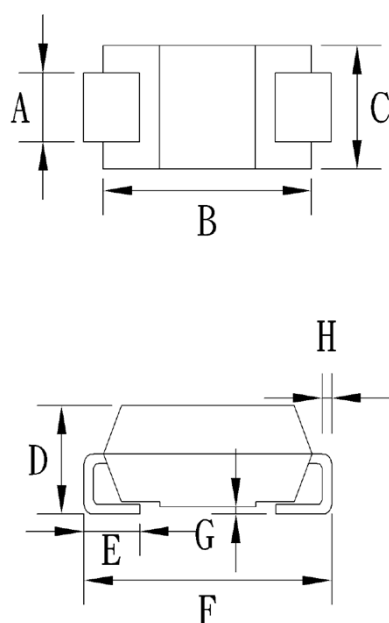


FIG.6 REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

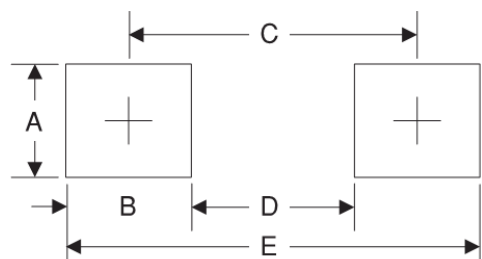


PACKAGE OUTLINE DIMENSIONS  
**DO-214AC (SMA)**



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.27	1.58	0.050	0.062
B	4.06	4.60	0.160	0.181
C	2.29	2.83	0.090	0.111
D	1.99	2.50	0.078	0.098
E	0.90	1.41	0.035	0.056
F	4.95	5.33	0.195	0.210
G	0.10	0.20	0.004	0.008
H	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.93	0.155
D	2.41	0.095
E	5.45	0.215

MARKING DIAGRAM



- P/N = Specific Device Code
- G = Green Compound
- YW = Date Code
- F = Factory Code

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